



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



LOC	DIST	REV	DATE	BY	CHK	APPV
A1	-	M9	14APR2011	RK	HMR	
		M10	01JUN2011	Kirs.	Merz	
		M11	17JUN2016	JJH	MC	

1 PRE TINNED  
vorverzinkt 1-2 µm

2 FINISH: ELECTROPLATED SILVER  
Oberfläche: galvanisch versilbert

ZONE "A": MIN 1-3 µm Ag  
min 1-3 µm Ag

ZONE "B": MIN 1-3 µm ELECTROPLATED SN  
min 1-3 µm galvanisch Sn

REST: SILVER OR TIN ALLOWED. IN TRANSITION AREAS  
OVERLAPPING LAYER OR PLAIN SURFACES ARE NOT ALLOWED.  
Silber oder Zinn erlaubt. Im Übergangsbereich sind keine  
überlappenden Schichten oder blanke Stellen erlaubt.

3 PLAIN  
blank

4 FINISH: ROLL-CLAD GOLD  
Oberfläche: walzplattiert Gold

ZONE "A": MIN 1.2 µm AuNi5 OVER 10±2 µm Ni INTERFACE LAYER  
min 1.2 µm AuNi5 ueber 10±2 µm Zwischenschicht

REST: MIN. 1-2 µm ELECTROPLATED Sn  
min. 1-2 µm galvanisch Sn

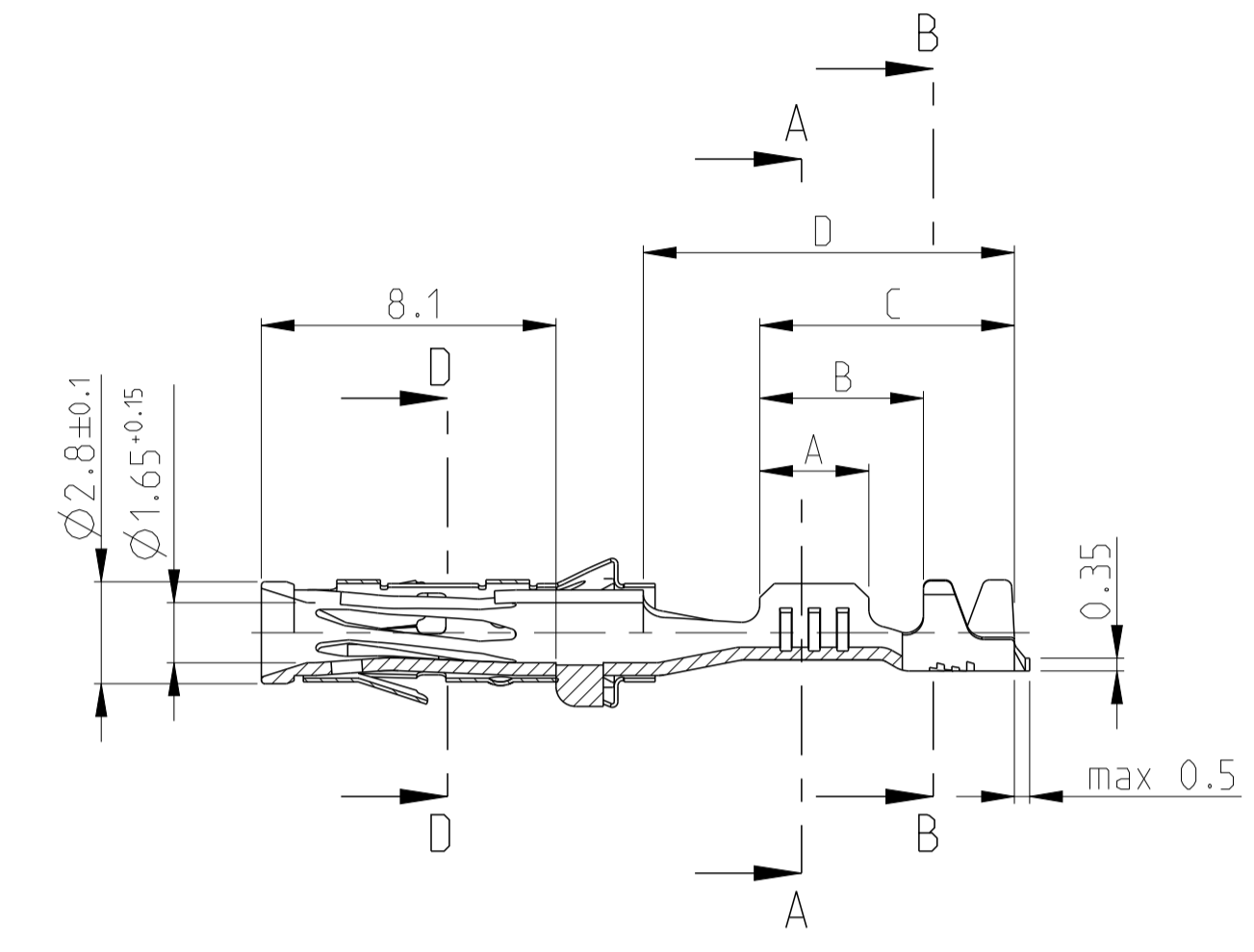
5 FINISH: ELECTROPLATED GOLD  
Oberfläche: galvanisch vergoldet

ZONE "A": MIN 0.8 µm ELECTROPLATED Au OVER MIN 1.3 µm ELECTROPLATED Ni LAYER  
AT CONTACT AREA  
min 0.8 µm galvanisch Au ueber min 1.3 µm galvanisch Ni Zwischenschicht  
im Kontaktbereich

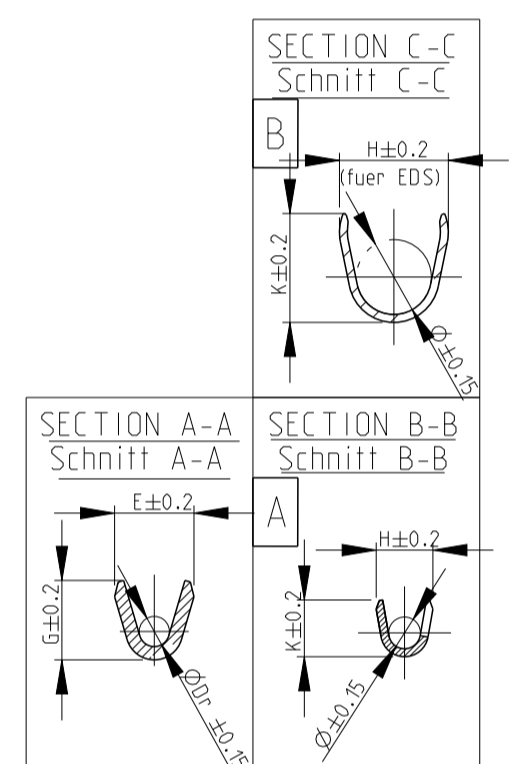
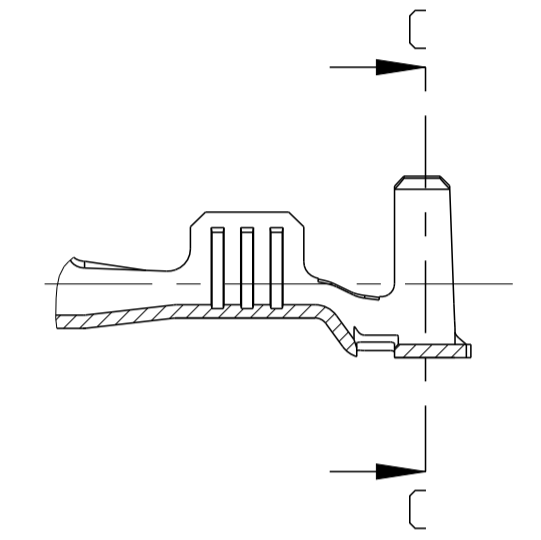
ZONE "B": MIN 1-2 µm ELECTROPLATED Sn OVER MIN 0.05 µm ELECTROPLATED Ni LAYER  
min 1-2 µm galvanisch Sn ueber min 0.05 µm galvanisch Ni Zwischenschicht

REST: Au, Sn OR Ni SURFACE. NO PLAIN SURFACES ALLOWED.  
Au, Sn ober Ni Oberfläche. Keine blanken Stellen erlaubt.

VERSION A  
(UNSEALED / ungedichtet)



VERSION B  
(SINGLE WIRE SEAL-SYSTEM /  
Einzel-Dichtungs-System)  
DGB 0.5 - 2.5 mm

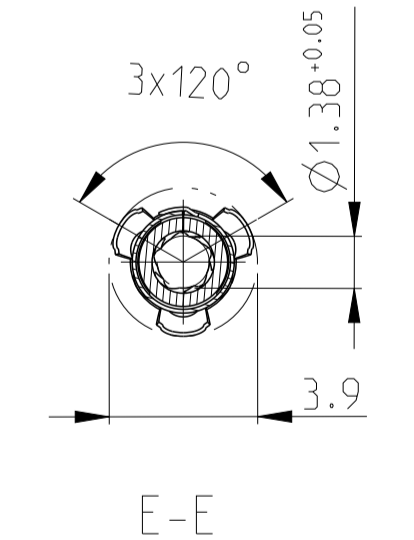
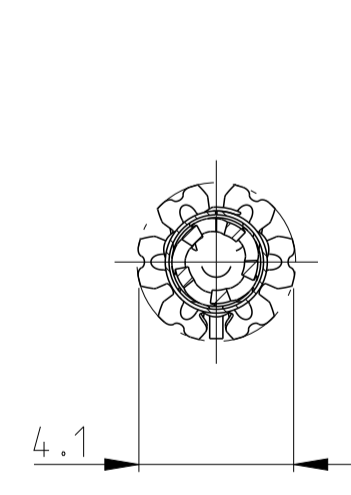
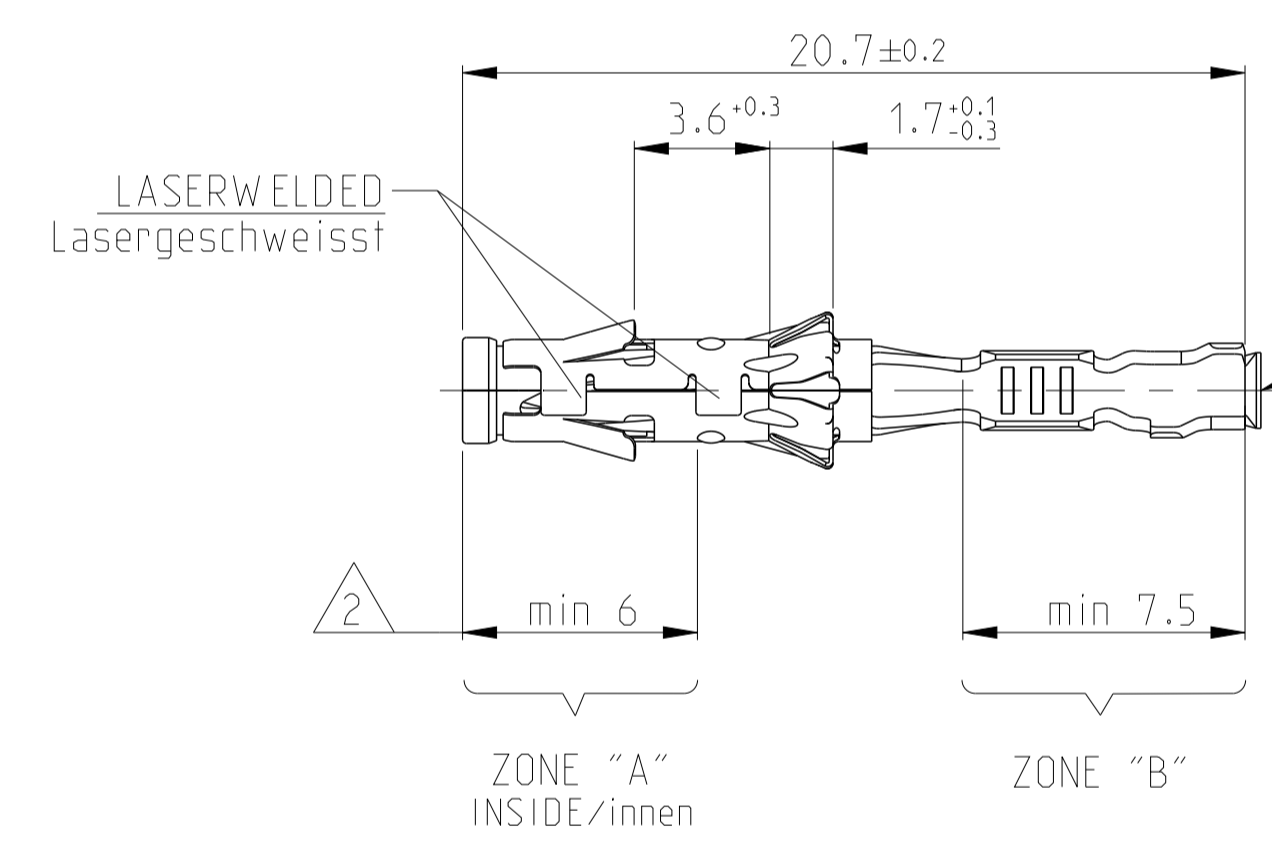


ORDER-No.  
SINGLE SEAL  
Einzeldichtung

ORDER-No.  
DEAD END PLUG  
Blindstopfen

M11	1-929990-0	1-962999-0	K	CuNi18Zn20	3	>1.0-2.5 FLR	2.2-3.0	E=3.6 G=3.8 Ø <sub>Dr</sub> =1.7	H=5.0 K=5.0 Ø=3.6	4	7.2	8.7	10.4	828905-1	828922-1
	929990-7	962999-7	K	CuNiSi	2										
	929990-4 SUPERSEDED BY 929990-1	962999-4	K	CuFe2	1										
	929990-3	-	K	CuNiSi	4										
	929990-1	962999-1	K	CuNiSi	1										
	1-929989-0	1-962998-0	A	CuNi18Zn20	3										
	929989-8	962998-8	A	CuNiSi	5										
	929989-7	962998-7	A	CuNiSi	2										
	929989-4	962998-4	M	CuFe2	1										
	929989-1	962998-1	M	CuNiSi	1										
	929988-4	962997-4	J	CuFe2	1										
	929988-2	962997-2	K	CuNiSi	2										
	929988-1	962997-1	J	CuNiSi	1										

Version A (UNSEALED / ungedichtet)	929987-4	962996-4	L	CuFe2	1	>1.0-2.5 FLR	1.9-3.0	E=3.6 G=3.8 Ø <sub>Dr</sub> =1.7	H=4.3 K=4.5 Ø=2.6	4	5.5	8.5	10.2		
	929987-1	962996-1	L	CuNiSi	1										
	929986-4	962995-4	L	CuFe2	1										
	929986-1	962995-1	L	CuNiSi	1										
	929985-4	962994-4	J	CuFe2	1										
	929985-1	962994-1	J	CuNiSi	1										



CUT-OFF FOR STRIP FORM AND LP-PARTS  
Trennstelle fuer Bandware und LP Teile

THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN Abraham, G.	17OCT2003	<b>STE</b> TE Connectivity	
DIMENSIONS: MASSENMESSEN (mm)		CHK Goedel, C.	18OCT2003		
TOLERANCES UNLESS OTHERWISE SPECIFIED: ALGEMEINTOLERANZEN		APV/D Bleicher, M.	22OCT2003	NAME DIA. 1.5mm SOCKET CONTACT Dia. 1.5mm Buchsenkontakt	
0 PLC ±0.15 2 PLC ± 3 PLC ±		PRODUCT SPEC 108-18028	APPLICATION SPEC VERARBEITUNGSPEC. 114-18040		RESTRICTED TO NUR FÜR
MATERIAL		WEIGHT GEWICHT	0.4g	SCALE MASSSTAB	5:1
FINISH/SCHLAEFEN		CUSTOMER DRAWING		SHEET BLATT	